

DC 4-Pin DIP Phototransistor Optocoupler

Features

- High isolation 5300 VRMS
- DC input with transistor output
- Operating temperature range 55 °C to 125 °C
- RoHS compliance
- REACH compliance
- Halogen free
- Regulatory Approvals
 - UL UL1577 (Pending Approval)
 - VDE EN60747-5-5 (Pending Approval)
 - CQC GB4943.1, GB8898 (Pending Approval)
 - IEC60065, IEC60950 (Pending Approval)

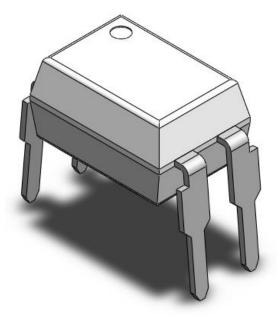
Description

The CT785 series consists of a photo transistor optically coupled to a gallium arsenide Infrared-emitting diode in a DIP package.

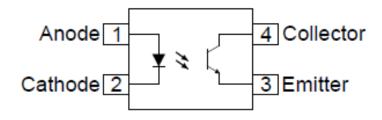
Applications

- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Schematic



CT785



DC 4-Pin DIP Phototransistor Optocoupler

Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5300	V _{RMS}	
Ртот	Total power dissipation	200	mW	
Topr	Operating temperature	-55 ~ +125	°C	
Тѕтс	Storage temperature	-55 ~ +150	°C	
TsoL	Soldering temperature	260	°C	
Emitter				
l _F	Forward current	60	mA	
I _{F(TRANS)}	Peak transient current (≤1µs P.W,300pps)	1000	mA	
VR	Reverse voltage	6	V	
PD	Emitter power dissipation	100	mW	
Detector				
Pc	Detector power dissipation	150	mW	
B _{VCEO}	Collector-Emitter Breakdown Voltage	80	V	
Bveco	Emitter-Collector Breakdown Voltage	7	V	
lc	Collector Current	80	mA	



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Electrical Characteristics $T_A = 25$ °C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	I _F = 10mA	-	1.2	1.3	V	
I _R	Reverse Current	V _R = 6V	-	-	5	μΑ	
Cin	Input Capacitance	f= 1MHz	-	10	30	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
Bvceo	Collector-Emitter Breakdown	I _C = 100μA	80	-	-	V	
B _{VECO}	Emitter-Collector Breakdown	I _{EC} = 100μA	7	-	-	V	
Land Collector Emitter Dark Current		V _{CE} = 24V, I _F = 0mA	-	-	100	nA	
ICEO	Collector-Emitter Dark Current	V _{CE} = 24V, I _F =0Ma , Ta=85°C			50	uA	

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Тур	Max	Units	Notes
	CTR Current Transfer Ratio	CT785GB	I _F = 5mA, V _{CE} = 5V	100		600	%	
CTR		CT785GR		100		300		
		CT785BLL		200		400		
	Saturated CTR	CT785GB	I _F = 1mA, V _{CE} = 0.4V	-	60		%	
CTR _(sat)		CT785GR		30	ı	ı		
		CT785BLL		-	60	ı		
V _{CE(SAT)}	Collector-Emitter Sa	aturation	I _F = 8mA, I _C = 2.4mA	-	0.2	0.4	V	
V CE(SAT)	Voltage		IF= OITIA, IC= 2.4ITIA	_	0.2	0.4	V	
Rio	Isolation Resistance		V _{IO} = 500V _{DC}	5x10 ¹⁰	ı		Ω	
Cıo	Isolation Capacitance		f= 1MHz	-	0.25	1	pF	

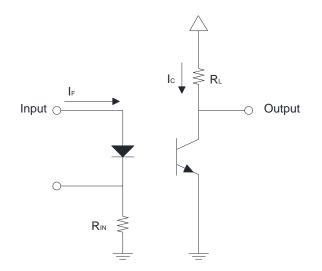


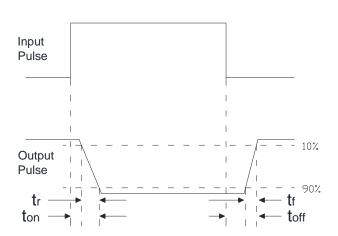
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Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
t _r	Rise Time		-		16	0	
t _f	Fall Time	I _C = 2mA, V _{CE} = 2V	-		16	μS	
ton	Turn-on time	R _L = 100Ω			20	0	
t _{off}	Turn-off time				20	μ\$	

Test Circuit

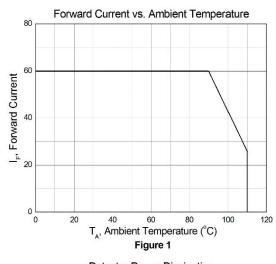


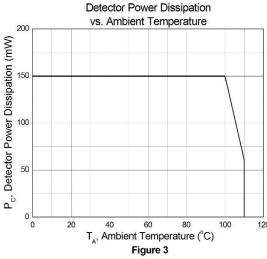


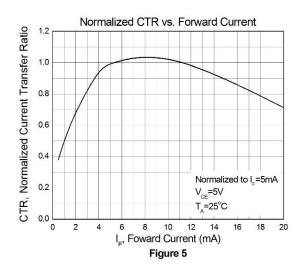


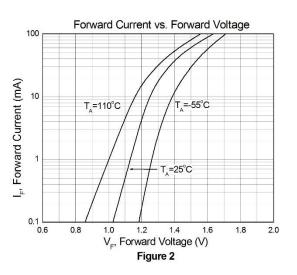


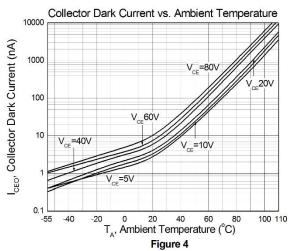
Typical Characteristic Curves

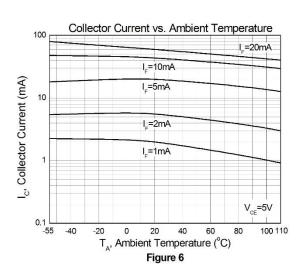






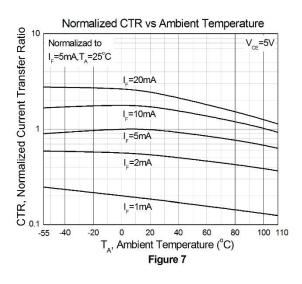


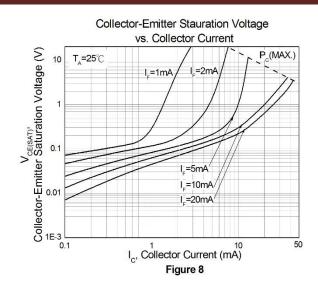


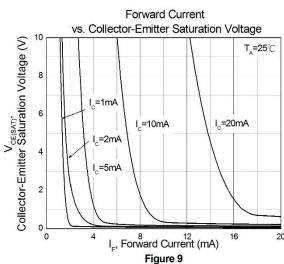


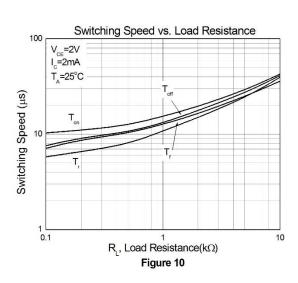


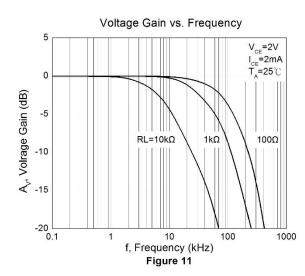
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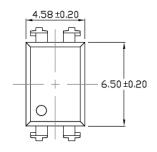


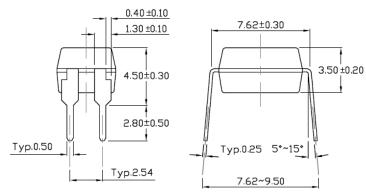




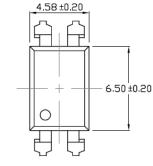
Package Dimension Dimensions in mm unless otherwise stated

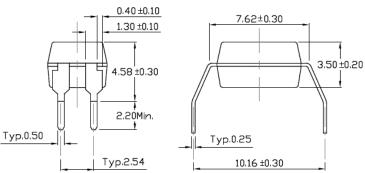
Standard DIP - Through Hole





Gullwing (400mil) Lead Forming – Through Hole (M Type)

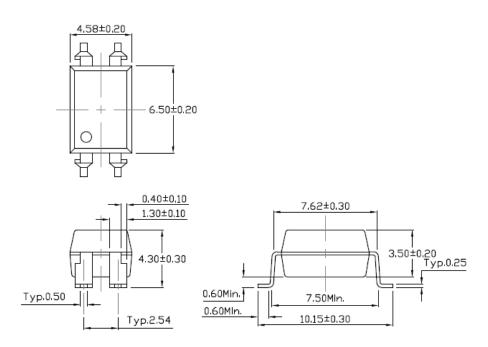




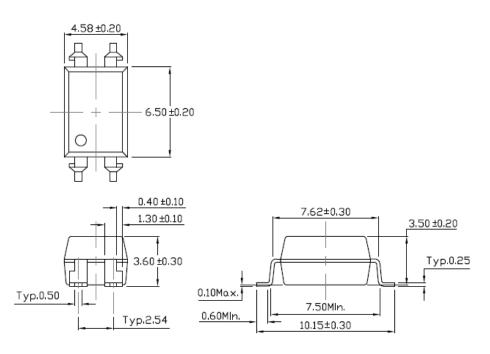




Surface Mount Lead Forming (S Type)



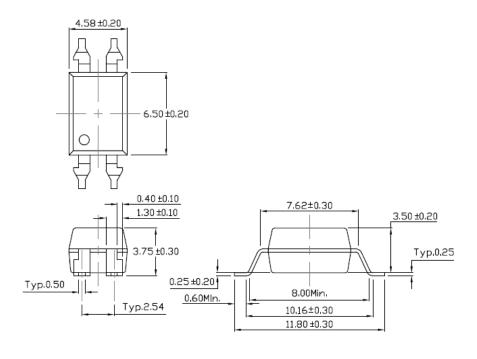
Surface Mount (Low Profile) Lead Forming (SL Type)







Surface Mount (Gullwing) Lead Forming (SLM Type)

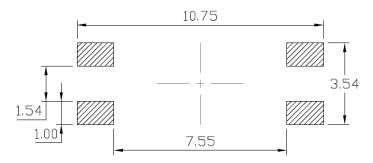




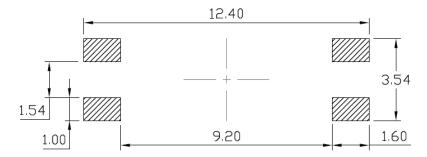


Recommended Solder Mask Dimensions in mm unless otherwise stated

Surface Mount Lead Forming & Surface Mount (Low Profile) Lead Forming



Surface Mount (Gullwing) Lead Forming



Marking Information



Note:

CT : Denotes "CT Micro"

785 : Part Number

X : "X" is CTR Rank (X= GB, GR, BLL)V : VDE Safety Option (V or none)

Y : Fiscal Year WW : Work Week

K : Manufacturing Code





Ordering Information

CT785X(V)(W)(Y)

CT : Denotes "CT Micro"

785 : Part Number

X: "X" is CTR Rank (X= GB, GR, BLL)

V : VDE Safety Option(V or none)

W: Lead form option (S, SL, SLM, M or none)

Y: Tape and reel option (T1, T2 or none)

Option	Option Description	
None	Standard 4 Pin DIP	100 Units/Tube
М	Gullwing (400mil) Lead Forming	100 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1500 Units/Reel
S(T2)	S(T2) Surface Mount Lead Forming – With Option 2 Taping	
SL(T1)	SL(T1) Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	
SL(T2)	SL(T2) Surface Mount (Low Profile) Lead Forming – With Option 2 Taping	
SLM(T1)	SLM(T1) Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	
SLM(T2) Surface Mount (Gullwing) Lead Forming – With Option 2 Taping		1500 Units/Reel



Wave soldering (JEDEC22A111 compliant)

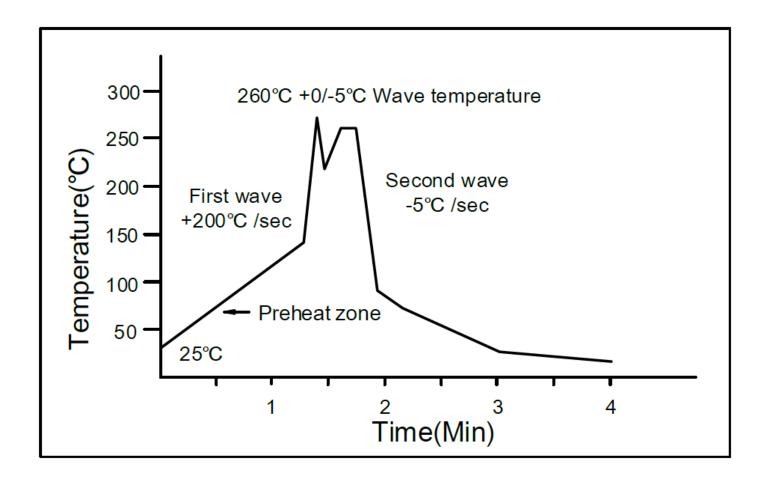
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Hand soldering by soldering iron

Allow single lead soldering in every single process.

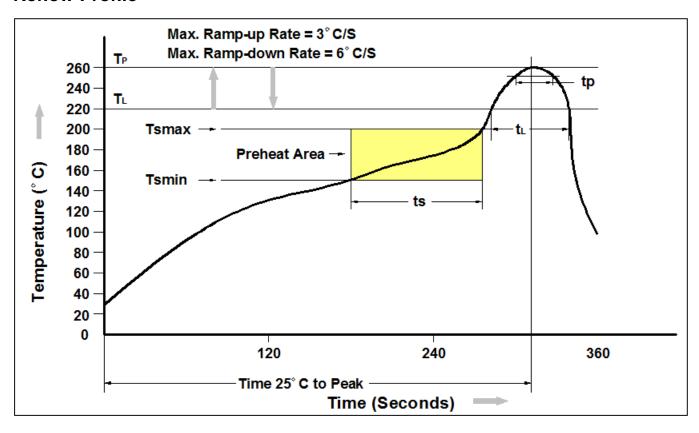
One time soldering is recommended. Temperature: 350+0/-5°C

Time: 3 sec max.





Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.



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